

FEATURES

- USB Type-C PD Source with PPS Supported
 - Compliant with USB Type-C Specification Reversion 2.1
 - Compliant with USB PD Specification Reversion 3.1
- Integrated VCONN Power for eMarker Detection
- Integrated high voltage driver for N-MOSFET
- Multiple DPDM Charging Protocols Implemented
 - BC1.2 DCP and Divider 3
 - QC2.0, QC3.0, AFC, FCP
- Up to 30 V Maximum Voltage Rating at USB Type-C Connector Pins
- Programmable Constant Voltage and Constant Current Control
- Fault Protections including Over-Voltage Protection, Over-current Protection, Short Circuitry Protection, Over-temperature Protection, Under-voltage Protection, CC Over-Voltage Protection, DPDM Over-Voltage Protection, Thermal Shut Down.
- Integrated MCU with MTP Memory.

- ± 6 kV HBM ESD Rating for all of Type-C Connector Pins

APPLICATIONS

Travel Adaptor
Car Charger

GENERAL DESCRIPTION

HUSB363 is designed for a USB Type-C PD Source product. It can support up to multiple PDOs with programmable voltage and current for different applications, such as PPS PDOs. All of PDOs are fully compliant with USB PD 3.1 Specification Rev.1.8.

Besides, HUSB363 implements DPDM charging protocols. Both D+ and D- pins can be configured to support QC2.0, QC3.0, AFC, FCP and divider 3 mode which provide excellent compatibility for the legacy devices.

It integrates an GATE driver to enable the VBUS from VIN to protect the devices connected with Type-C connector.

The high voltage tolerance and protections at CC1, CC2, D+ and D- pins provide more reliability for the system.

TYPICAL APPLICATION CIRCUIT

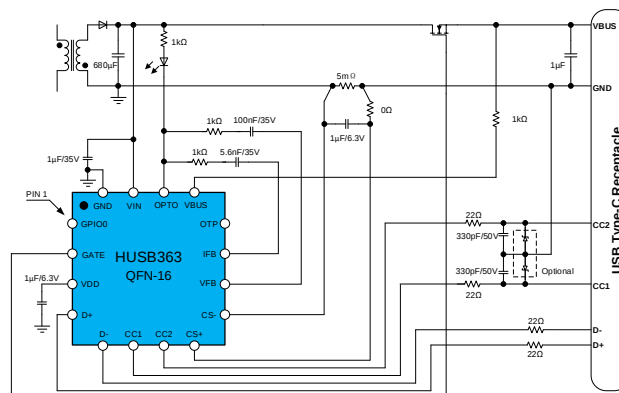


Figure 1. Typical Application Circuit

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REVISION HISTORY

Version	Date	Descriptions
Rev. 1.0	08/2023	Initial version
Rev. 1.1	08/2023	Modify ESD parameters

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

TOP VIEW

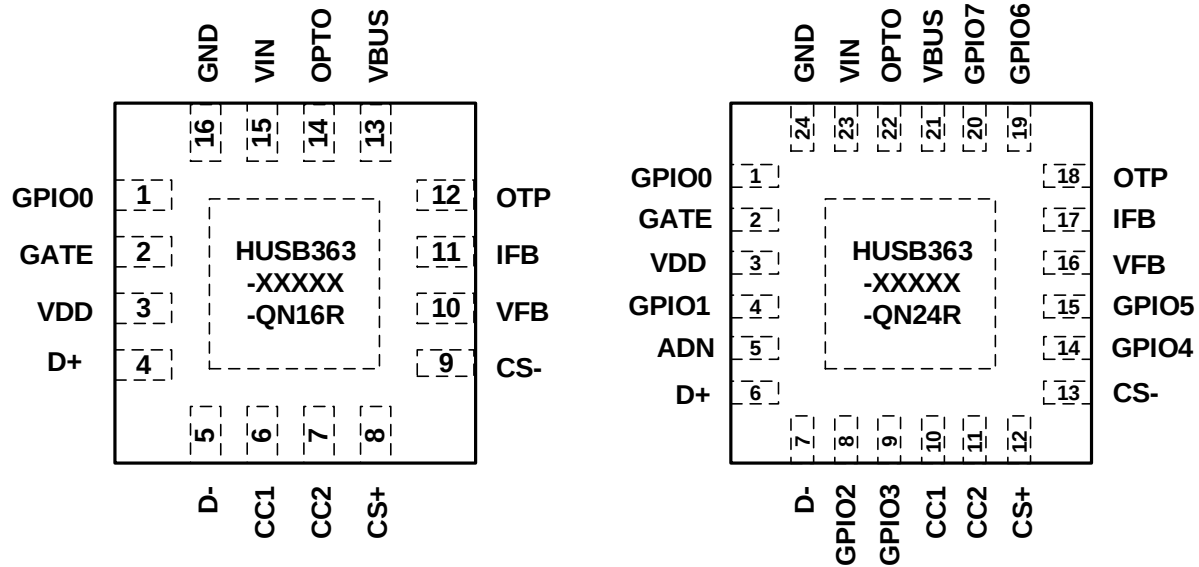


Figure 2. HUSB363 Pin Assignment

Table 1. HUSB363-XXXXX-QN16R Pin Function Descriptions

Pin No.	Pin Name	Type	Description
1	GPIO0	AO	General purpose pin 0. This pin is only open drain output.
2	GATE	AO	N-MOSFET Gate driver output for VBUS load switch.
3	VDD	P	Internal 1.5 V regulator output for system power. Connect a 1 μ F ceramic capacitor at this pin.
4	D+	DIO	USB D+ line.
5	D-	DIO	USB D- line.
6	CC1	AIO	USB Type-C CC1 line.
7	CC2	AIO	USB Type-C CC2 line.
8	CS+	AI	Positive input of the current sense amplifier.
9	CS-	AI	Negative input of the current sense amplifier.
10	VFB	AI	Feedback point of Constant Voltage (CV) loop, connect CV compensation network to this pin.
11	IFB	AI	Feedback point of Constant Current (CC) loop, connect CC compensation network to this pin.
12	OTP	AI	External temperature sensing pin. An internal pull up current source is connected at this pin. A NTC thermistor is recommended to be place at this pin.
13	VBUS	AI	VBUS sense and discharge pin.
14	OPTO	AI	OPTO driver. Connect to the opto-coupler in isolated ACDC applications.
15	VIN	P	Supply voltage input. Connect this pin to GND via a recommended 1 μ F ceramic capacitor.
16	GND	P	Power ground.
-	PAD	-	QFN package pad. It is recommended to connect this pin to GND.

Table 2. HUSB363-XXXXX-QN24R Pin Function Descriptions

Pin No.	Pin Name	Type	Description
1	GPIO0	AO	General purpose pin 0. This pin is only open drain output.
2	GATE	AO	N-MOSFET Gate driver output for VBUS load switch.
3	VDD	P	Internal 1.5 V regulator output for system power. Connect a 1 μ F ceramic capacitor at this pin.
4	GPIO1	AO	General purpose pin 1. This pin is only open drain output.
5	ADN	AI	ADC input pin for voltage detection.
6	D+	DIO	USB D+ line.
7	D-	DIO	USB D- line.
8	GPIO2	DIO	General purpose pin 2. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
9	GPIO3	DIO	General purpose pin 3. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
10	CC1	AIO	USB Type-C CC1 line.
11	CC2	AIO	USB Type-C CC2 line.
12	CS+	AI	Positive input of the current sense amplifier.
13	CS-	AI	Negative input of the current sense amplifier.
14	GPIO4	AO	General purpose pin 4. This pin is only open drain output.
15	GPIO5	AO	General purpose pin 5. This pin is only open drain output.
16	VFB	AI	Feedback point of Constant Voltage (CV) loop, connect CV compensation network to this pin.
17	IFB	AI	Feedback point of Constant Current (CC) loop, connect CC compensation network to this pin.
18	OTP	AI	External temperature sensing pin. An internal pull up current source is connected at this pin. A NTC thermistor is recommended to be place at this pin.
19	GPIO6	DIO	General purpose pin 6. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
20	GPIO7	DIO	General purpose pin 7. This pin can be configured as ADC input, digital input, digital output, pull up or pull down function by firmware.
21	VBUS	AI	VBUS sense and discharge pin.
22	OPTO	AI	OPTO driver. Connect to the opto-coupler in isolated ACDC applications.
23	VIN	P	Supply voltage input. Connect this pin to GND via a recommended 1 μ F ceramic capacitor.
24	GND	P	Power ground.
-	PAD	-	QFN package pad. It is recommended to connect this pin to GND.

1 Legend:

A = Analog Pin

P = Power Pin

D = Digital Pin

I = Input Pin

O = Output Pin

RECOMMENDED OPERATING CONDITIONS

Table 3.

Parameter	Rating
V _{IN} Input Voltage	3.15 V to 23 V
Operating Junction Temperature Range (T _J)	-40 °C to 125 °C
Ambient Temperature Range (T _A)	-40 °C to 85 °C

SPECIFICATIONS

V_{IN} = 3.15 V to 23 V, T_J = -40°C to 125°C for minimum and maximum specifications, and T_A = 25°C for typical specifications, unless otherwise noted.

Table 4. Electrical Characteristics

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
Power Supply						
Supply Voltage	V _{IN_UVLO}	Rising edge		3.3		V
UVLO Threshold						
Supply Voltage	V _{IN_UVLO_HYS}			300		mV
UVLO Hysteresis						
Operation Mode	I _{CC_OPR}	CC is attached with a R _d , normal operation		4		mA
Supply Current						
Sleep Mode Supply	I _{CC_SLP}	CC is attached with a R _d , configured in sleep mode			1.5	mA
Current						
Internal Regulator (VDD)						
Output Voltage	V _{DD}			1.5		V
Type C Function (CC1, CC2)						
Default Current Source	I _{RP_DFT}		64	80	96	μA
1.5 A Current Source	I _{RP_1.5A}		166	180	194	μA
3 A Current Source	I _{RP_3A}		304	330	356	μA
Rd Detection Threshold 1	V _{Rd_OPEN_1.5A}	Default or 1.5 A R _p current source is enabled, T _A = 25°C	1.55	1.6	1.65	V
Rd Detection Threshold 2	V _{Rd_OPEN_3A}	3 A R _p current source is enabled, T _A = 25°C	2.50	2.6	2.70	V
Ra Detection Threshold 0	V _{Ra_DEF}	Default R _p current source is enabled, T _A = 25°C	0.15	0.2	0.25	V
Ra Detection Threshold 1	V _{Ra_1.5A}	1.5 A R _p current source is enabled, T _A = 25°C	0.35	0.4	0.45	V
Ra Detection Threshold 2	V _{Ra_3A}	3 A R _p current source is enabled, T _A = 25°C	0.75	0.8	0.85	V
CC Impedance in Disable Mode	R _{P_DIS}	CC impedance with R _P is disabled	2			MΩ
VCONN Output Voltage	V _{VCONN}	VCONN is enabled	3	5	5.5	V
VCONN Output Current Limit	I _{VCONN}	V _{IN} = 3.3 V to 5.5 V and VCONN is enabled	20			mA
Type C PD BMC Receiver						
Noise Amplitude when BMC is Active	V _{NoiseActive}	Peak-to-peak noise after Rx filter has been applied			165	mV
Noise Amplitude when BMC is Idle	V _{NoiseIdle}	Peak-to-peak noise after Rx filter has been applied			300	mV

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
Receiver Input Impedance	ZBmcRx	Input impedance of Rx	2			MΩ
Rx Bandwidth Limiting Filter	tRxFilter	Time constant of a single pole filter	100			ns
Type C PD BMC Transmitter						
Bit Rate	fBitRate	Refer the average bit rate of the last 32b of the Preamble	270	300	330	kbps
Unit Interval	UI		3.03	3.33	3.7	μs
Bitrate Drift	pBitRate				0.25	%
Fall Time	tFall	10% and 90% amplitude points, unloaded condition	300			ns
Rise Time	tRise	10% and 90% amplitude points, unloaded condition	300			ns
Voltage Swing	VSwing	CC pull down resistor >800 Ω	1.05	1.125	1.2	V
Voltage Low	VLow	CC pull down resistor >800 Ω	-75	0	75	mV
Transmitter output impedance	ZDriver		33	50	75	Ω
BC1.2 DCP MODE						
D+ and D- Shorting Resistance	RDPM_SHORT	V _{D+} = 0.6 V		30		Ω
D+ Leakage Resistance	RDP_LKG	V _{D+} = 0.6 V		800		kΩ
D- Leakage Resistance	RDM_LKG	V _{D-} = 0.6 V		800		kΩ
DIVIDER 3 MODE						
D+ Output Voltage	V _{DP_2.7V}	V _{IN} = 5 V		2.7		V
D- Output Voltage	V _{DM_2.7V}	V _{IN} = 5 V		2.7		V
D+ Output Impedance	RDP_PAD	I _{D+} = -5 μA		30		kΩ
D- Output Impedance	RDM_PAD	I _{D-} = -5 μA		30		kΩ
HVDCP MODE						
Output Voltage Selection Reference	V _{SEL_REF}			2.0		V
Data Detect Voltage	V _{DAT_REF}			0.325		V
D- Pull-Down Resistance	RDM_DWM			15		kΩ
FCP MODE						
D- FCP TX Valid Output High	V _{TX_VOH}		2.55		3.6	V
D- FCP TX Valid Output Low	V _{TX_VOL}				0.3	V
D- FCP RX Valid Input High	V _{RX_VIH}		1.4		3.6	V
D- FCP RX Valid Input Low	V _{RX_VIL}				1	V
Unit Interval for FCP	UI			160		μs
Voltage Regulation						
VDAC LSB	LSB_VDAC			10		Bit
Default Voltage	V _{DEFAULT}		4.75	5.1	5.5	V
Regulation Accuracy	V _{SRCValid}	T _A = 25°C	99	100	101	%
		T _J = -40°C to 125°C	97	100	103	%
Active Load for Discharge	R _{ALD}	ALD option 0 is selected		70		mA

Parameter	Symbol	Test Conditions/Comments	Min	Typ	Max	Unit
		ALD option 1 is selected		100		mA
		ALD option 2 is selected		140		mA
		ALD option 3 is selected		170		mA
Current Control						
Constant Current Accuracy		Operating current is less than 3 A	-0.15	0	0.15	A
		Operating current is higher than 3 A, refer to nominal operation current	95	100	105	%
Current Sensing Resistor	R _{CS}			5		mΩ
Gate Driver and VBUS						
Gate Driver Output Voltage	V _{GATE}	V _{IN} ≤ 21 V	5	7	10	V
		V _{IN} > 21 V	4.5	5.5	6.5	V
Gate Driver Output Current	I _{GATE_ON}			20		μA
Gate Discharge Current	I _{GATE_DSG}			20		mA
VBUS Discharge Current	I _{VBUS_DSG}			20		mA
Fault Protection						
Over-voltage Protection Threshold	V _{IN_OV}	OVP threshold option 0, refer to nominal V _{IN}		110		%
		OVP threshold option 1, refer to nominal V _{IN}		115		%
		OVP threshold option 2, refer to nominal V _{IN}		120		%
		OVP threshold option 3, refer to nominal V _{IN}		125		%
Over-current Protection Threshold	I _{IN_OCP}	Nominal output current = 3 A		3.6		A
Short-circuit Protection Threshold	I _{IN_SCP}			12		A
OTP Current Source	I _{OTP}			80		μA
Thermal Shut Down Threshold	T _{SD}			150		°C
Thermal Shut Down Hysteresis	T _{SDHys}			20		°C
ADC						
ADC Resolution	N _{ADC}			11		Bit
ADC Reference Voltage	V _{ADC}			2.5		V
ADC Sample Rate	f _{ADC}			125		kHz
GPIO						
Digital Output High Voltage	V _{OH_D}	Source current = 2 mA		3.3		V
Digital Output Low Voltage	V _{OL_D}	Sink current = 2 mA			0.4	V
Digital Input High Voltage	V _{IH_D}		1.4			V
Digital Input Low Voltage	V _{IL_D}				1	V
Internal Pull-up Resistor	R _{GPIO_PU}			35		kΩ
Internal Pull-down Resistor	R _{GPIO_PD}			35		kΩ

ABSOLUTE MAXIMUM RATINGS

Table 5.

Parameter	Rating
VIN, VBUS, OPTO, GATE to GND	–0.3 V to 30 V
CC1, CC2, D+, D-, CS+, CS- to GND	–0.3 V to 30 V
VFB, IFB, ADN, OTP, GPIO0, GPIO1, GPIO2, GPIO3, GPIO4, GPIO5, GPIO6, GPIO7 to GND	–0.3 V to 7 V
VDD to GND	–0.3 V to 2 V
Junction Temperature Range	–40°C to 125°C
Soldering Conditions	JEDEC J-STD-020
Electrostatic Discharge (ESD)	
Human Body Model (All PIN to GND)	±7000 V
Human Body Model (All PIN to VIN)	±2500 V
Charged Device Model	±2000 V

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Thermal performance is directly linked to printed circuit board (PCB) design and operating environment. Close attention to PCB thermal design is required.

θ_{JA} is the natural convection junction to ambient thermal resistance measured in a one cubic foot sealed enclosure.

θ_{JC} is the junction to case thermal resistance.

Table 6. Thermal Resistance

Package Type	θ_{JA}	θ_{JC}	Unit
QFN4x4-16L	47	22	°C/W
QFN4x4-24L	46	23	°C/W

ESD CAUTION



Electrostatic Discharge Sensitive Device.

Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

FUNCTIONAL BLOCK DIAGRAM

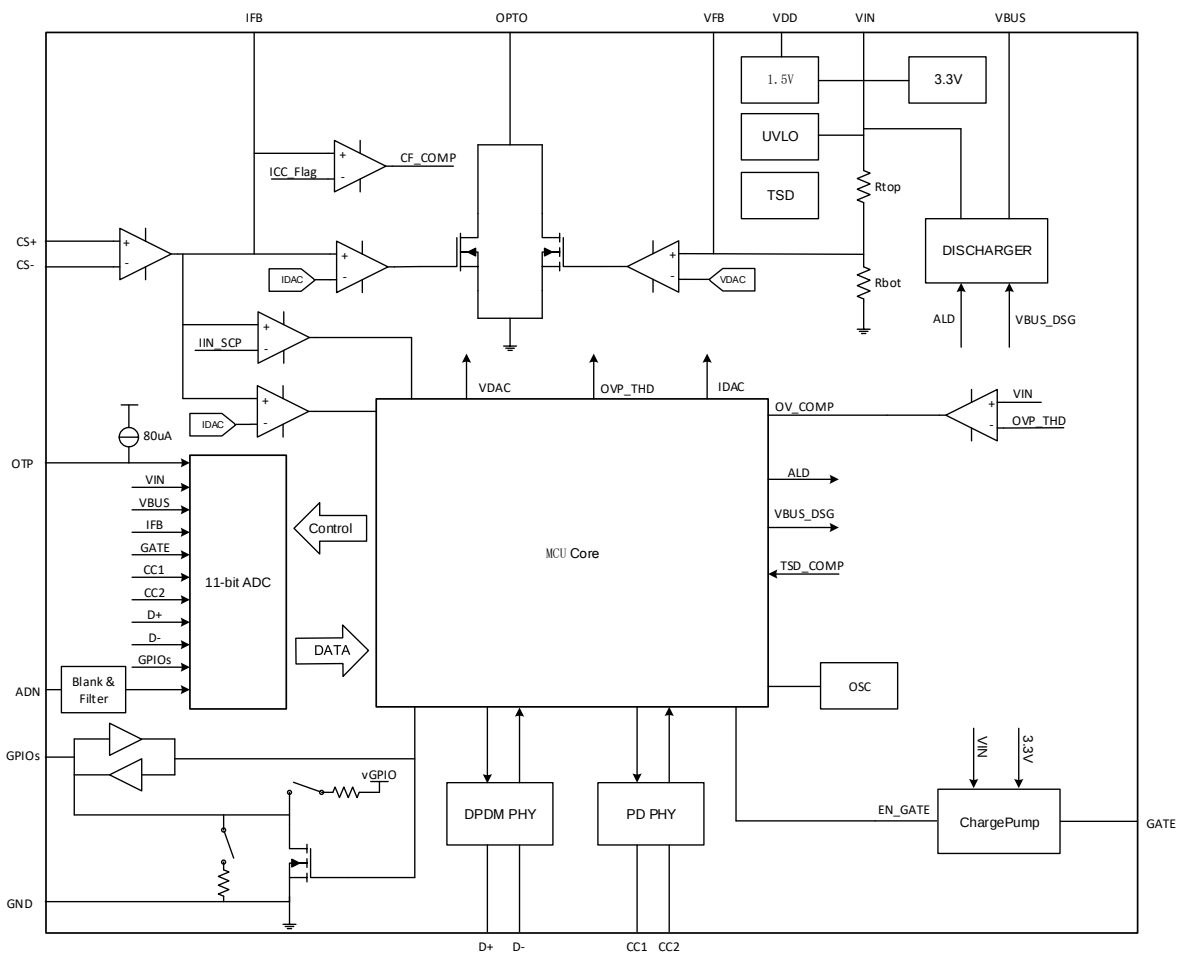


Figure 3. HUSB363 Functional Block Diagram

THEORY OF OPERATION

HUSB363 is a MCU-based USB PD Source controller. It integrates a MCU core with necessary functions for USB PD protocol, legacy charging protocols and power regulation. By modifying the firmware, the HUSB363 can be employed in different applications. The integrated protections including OCP, OVP, UVP, SCP, OTP, CCOV, TSD and DPDMOV can enhance the system reliability significantly.

MCU

HUSB363 integrates a MCU for the main operation. This subsystem implements the standard firmware structure. It features:

- Support the programs in C format
- Support interruptions
- Internal communication BUS

VIN PIN

VIN pin is the power supply input, which is derived from the output of the AC-DC or DC-DC converter. Connect a 1 μ F decoupling MLCC between VIN pin and GND pin.

The VIN pin is also connected to an internal MOSFET and discharge resistor, which is used as a bleeder to help discharge the energy stored in the output capacitor. With this bleeder, VIN can be regulated to vSafe5V upon the detachment of a connected device, or to a lower desired output voltage level upon a request command received from the Sink, such as from 20 V to 5 V.

VDD PIN

An internal liner regulator is used to provide 1.5 V for internal circuits. Connect a 1 μ F MLCC to VDD pin for decoupling.

CONTROL LOOP COMPENSATION CIRCUIT (VFB, CS+, CS-, IFB, OPTO PINS)

In the [HUSB363](#), the constant voltage loop (CV loop) compensation and constant current loop (CC loop) compensation are implemented. VIN voltage is scaled by a resistor divider to be as the feedback voltage. It is compared with the internal voltage reference to generate an error signal. The CV loop can compensate this error signal. And then the compensated signal is employed to drive the primary side of the opto-coupler and control the AC-DC power loop.

CURRENT SENSE RESISTOR

The recommended current sense resistor is 5 m Ω . The sensed current information is employed to perform OCP, SCP and Constant Current Control.

CC1 AND CC2 PINS

CC1 and CC2 pins are used to detect Type-C connection, BMC communication.

BMC DRIVER

Through the Type-C detection, one of the CC pins will be connected to the internal BMC block to achieve PD communication.

VBUS PIN

This pin is used to sense VBUS presence and discharge VBUS voltage on USB Type-C receptacle side.

The VBUS pin is also connected to an internal MOSFET and discharging circuitry, which is used as a bleeder to help dissipate the energy stored in the VBUS capacitor. With this bleeder, VBUS is discharged to vSafe0V upon the detachment of a connected device, or to a lower desired output voltage level upon a request command received from the Sink, such as from 20 V to 5 V.

GATE PIN

The GATE pin of the [HUSB363](#) is designed to drive an external N-MOSFET. When the [HUSB363](#) is attached and is ready to enable VBUS. The GATE pin outputs a voltage to turn on the external N-MOSFET. The turn on time of the external N-MOSFET may impacted by the external N-MOSFET's characteristics.

OVER VOLTAGE PROTECTION

The **HUSB363** detects the VIN pin voltage to achieve over-voltage protection function. The threshold to trigger over-voltage protection can be configured as 4 options. When the over-voltage condition occurs, the firmware is notified to handle this fault.

OVER CURRENT PROTECTION

When the current sensed by the sense resistor exceeds the pre-set threshold in firmware. The threshold to trigger over-current protection can be configured by firmware. When the over-current condition occurs, the firmware is notified to handle this fault.

SHORT CIRCUIT PROTECTION

The **HUSB363** integrates SCP protection function. When the VBUS is hard shorted to GND by fault, the output current increases sharply. When the output current reaches the SCP threshold, the firmware is notified to handle this fault.

OVER TEMPERATURE PROTECTION

The **HUSB363** integrates a current source at OTP pin. When the OTP function is preferred, a NTC thermistor is recommended to be place at OTP pin. In addition, the internal current source outputs the current to the GND through the external thermistor. The voltage at the OTP pin can be sampled by ADC to identify the actual temperature.

THERMAL SHUTDOWN

When the junction temperature rises across T_{TSD} , thermal shut down takes action and the GATE is disabled. When the junction temperature falls across $T_{TSD}-T_{TSD_HYS}$, the **HUSB363** reset to default mode and will automatic recover again.

DPDM PROTOCOL

The **HUSB363** supports various fast charging protocols including BC1.2 DCP, Divider 3, QC 2.0/3.0, AFC, FCP and SCP. According to the different status of D+ and D- pins, the **HUSB363** recognizes the attached Sinks and apply the fast charging protocol automatically.

GPIO

Interrupt Input: the GPIO pin is a digital input pin, any digital logic level transition of GPIO pin can be configured a interrupt source to notify the MCU.

Output Pin: the GPIO pin is a digital output pin, the output state can be determined by the firmware.

ADC Input: the GPIO pin is an analog input pin, the input voltage can be sampled by ADC and reported to the MCU.

	INT	ADC	Pull UP	Pull Down	Open Drain	Direct output	UART
GPIO0					○		
GPIO1					○		
GPIO2	○	○	○	○	○	○	○
GPIO3	○	○	○	○	○	○	○
GPIO4					○		
GPIO5					○		
GPIO6	○	○	○	○	○	○	
GPIO7	○	○	○	○	○	○	

TYPICAL APPLICATION CIRCUITS

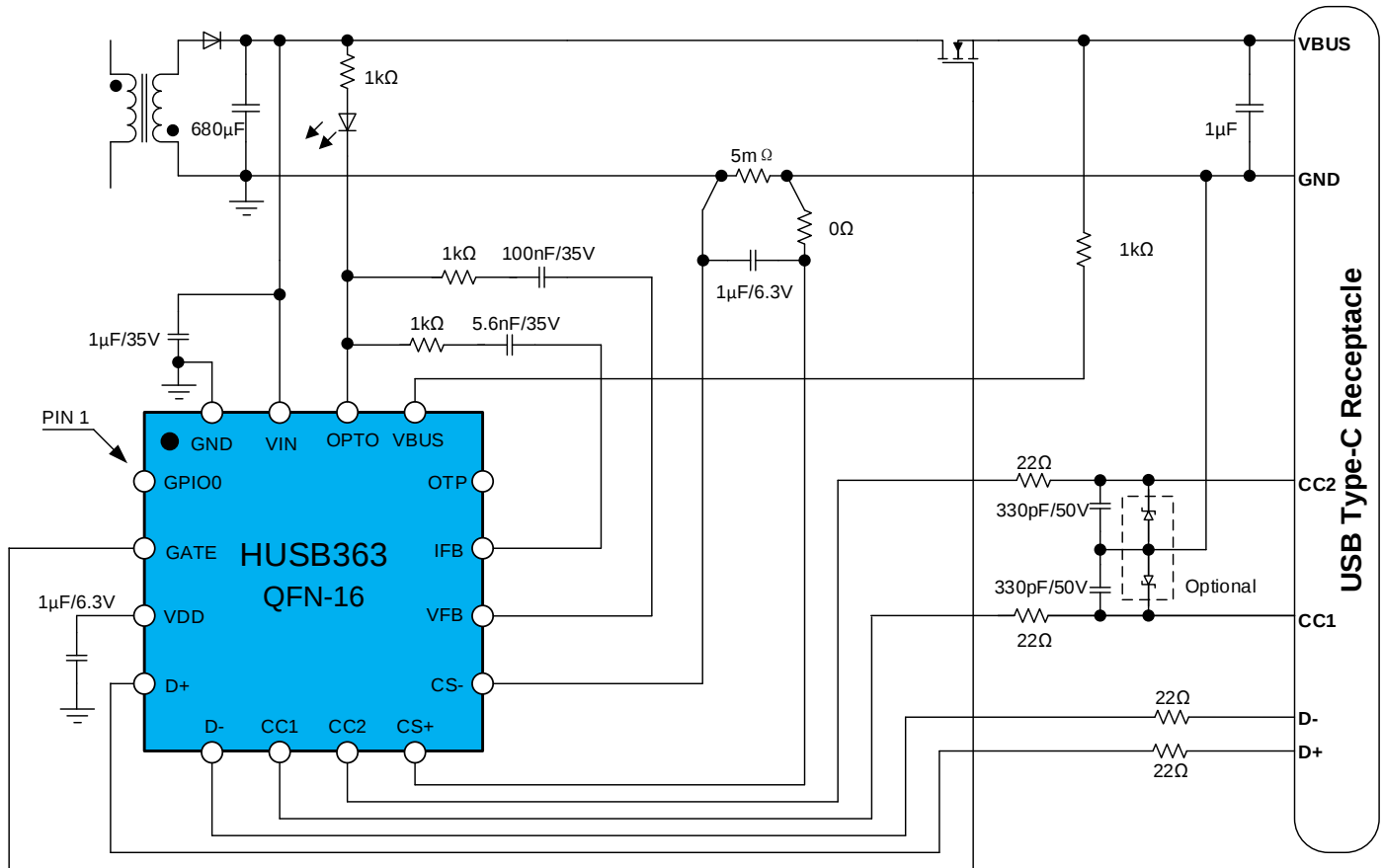


Figure 4. QFN-16 Typical Application

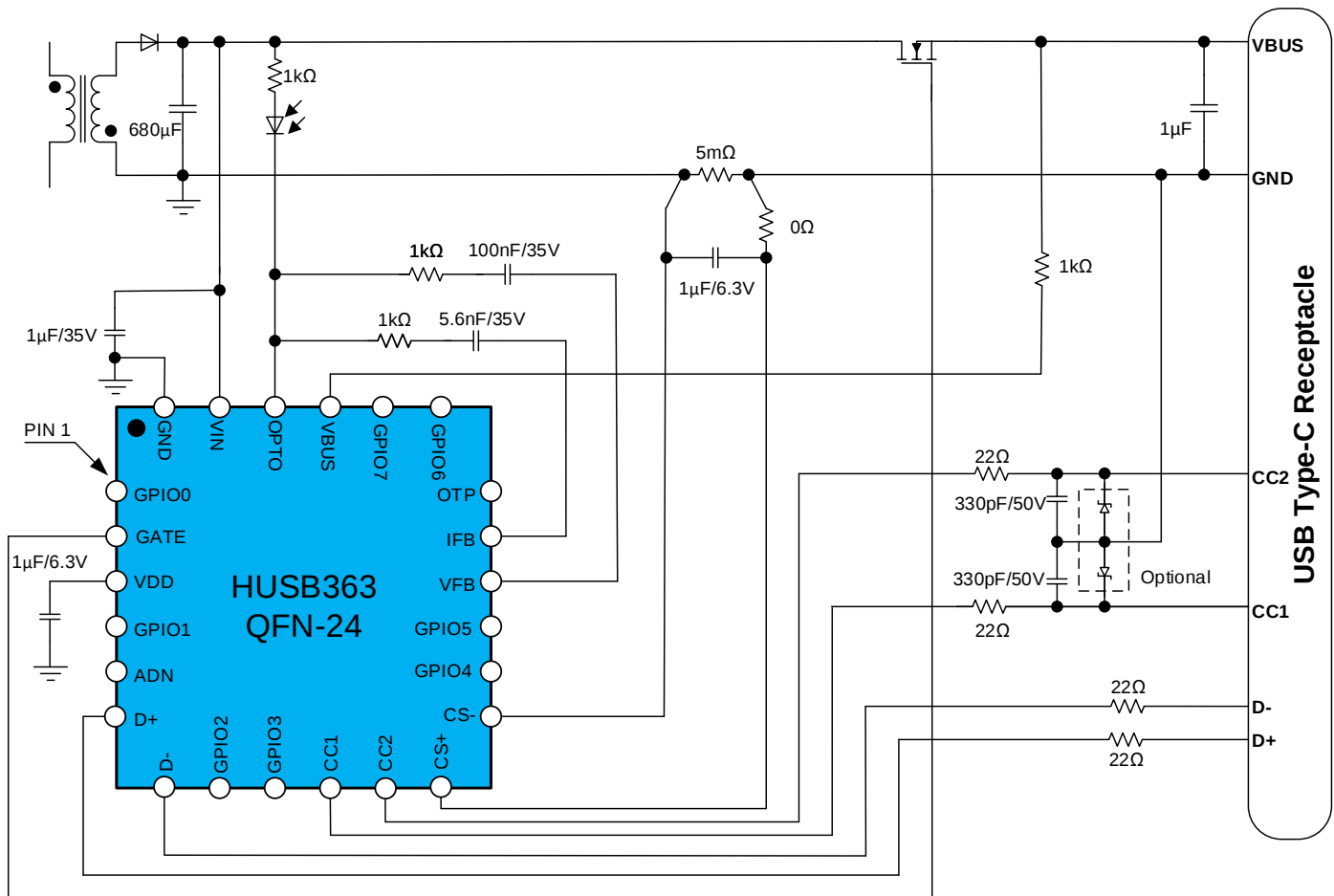
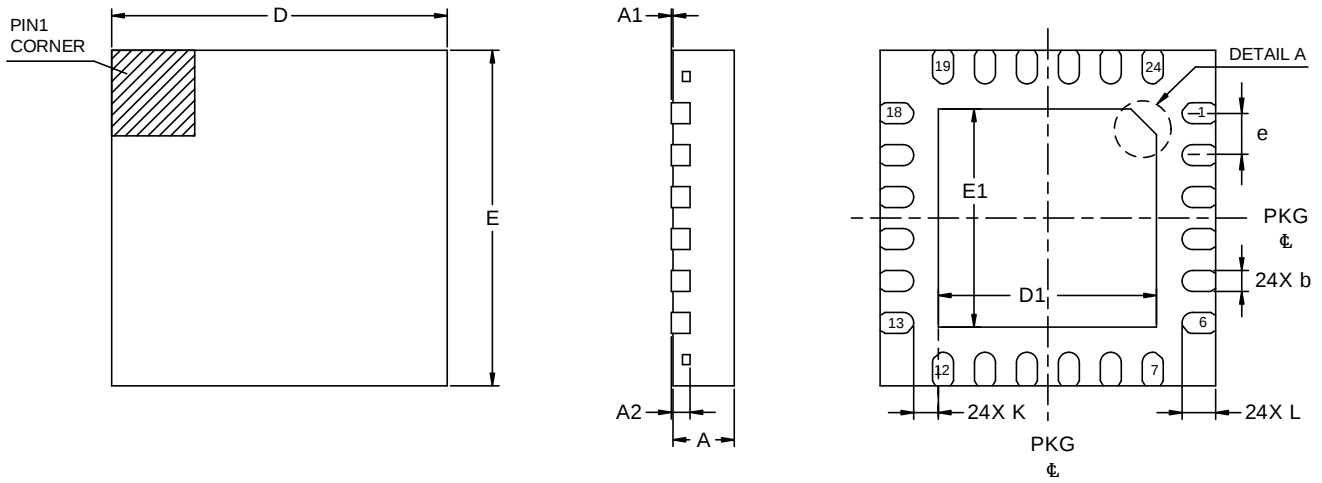


Figure 5. QFN-24 Typical Application

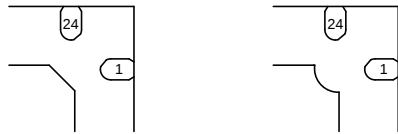
PACKAGE OUTLINE DIMENSIONS



TOP VIEW

SIDE VIEW

BOTTOM VIEW



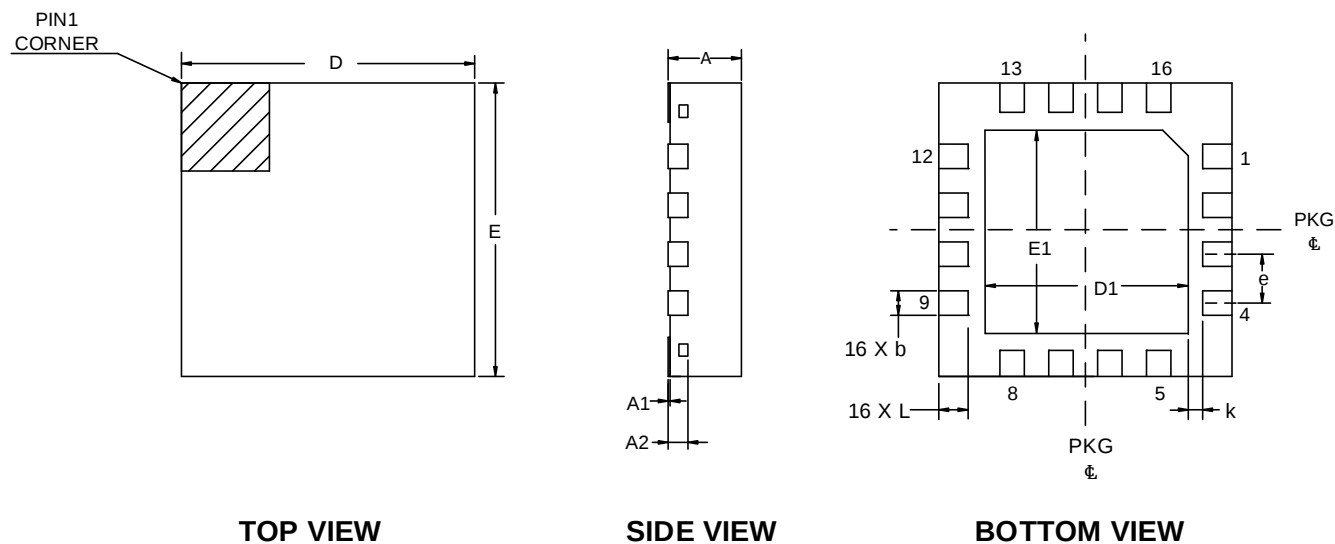
ALTERNATE A-1

ALTERNATE A-2

DETAIL A: ALTERNATE PIN#1 ID. CONSTRUCTIONS

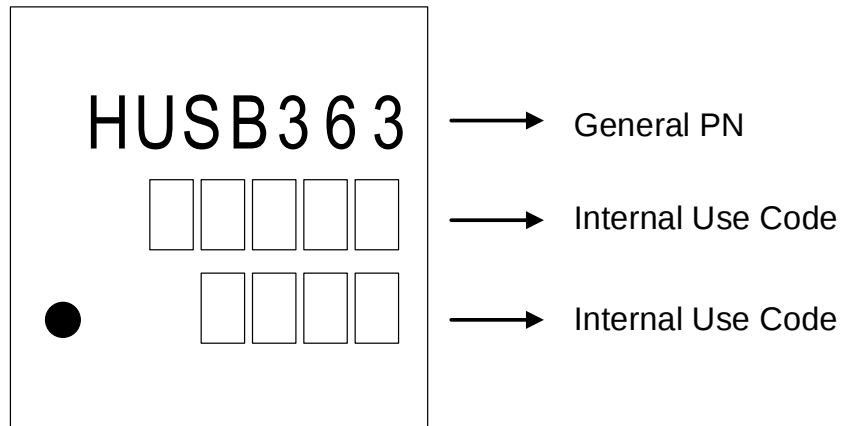
SYMBOLS	DIMENSION IN MILLIMETERS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.000	0.02	0.05
A2	0.203 REF		
b	0.20	0.25	0.30
D	4.00 BSC		
E	4.00 BSC		
D1	2.40	2.70	2.80
E1	2.40	2.70	2.80
e	0.50 BSC		
L	0.30	0.40	0.50
k	0.20 MIN		

Figure 6. QFN4x4-24L Package of Dimension



SYMBOLS	DIMENSION IN MILLIMETERS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.000	0.02	0.05
A2	0.203 REF		
b	0.25	0.30	0.35
D	4.00 BSC		
E	4.00 BSC		
D1	2.60	2.70	2.80
E1	2.60	2.70	2.80
e	0.65 BSC		
L	0.30	0.40	0.50
k	0.25 REF		

Figure 7. QFN4x4-16L Package of Dimension

PACKAGE TOP MARKING

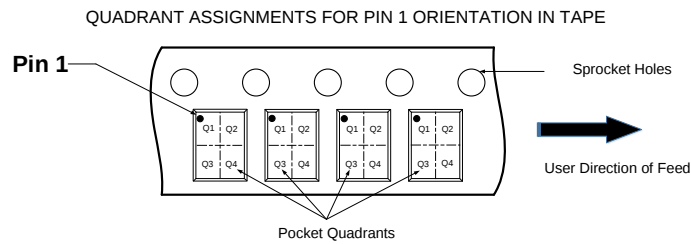
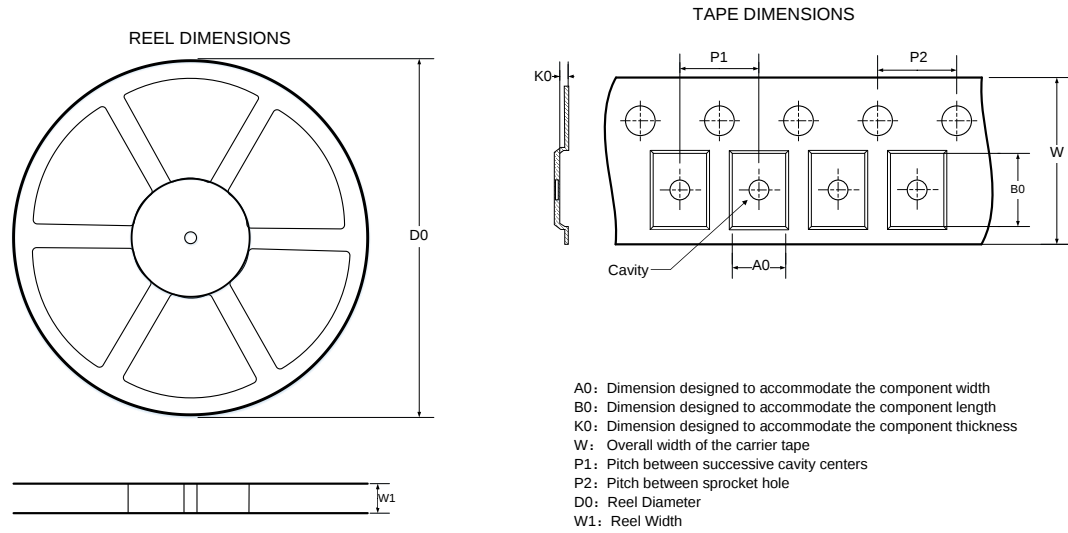
QFN4X4-24L & QFN4X4-16L

Figure 8. marking

ORDERING GUIDE

Model	Temperature Range	MSL	Package Type	Package Option	Package Qty
HUSB363-XXXXX-QN16R	-40 to 125°C	MSL3	QFN-16L, 4 mm x 4 mm	Tape & Reel	5000
HUSB363-XXXXX-QN24R	-40 to 125°C	MSL3	QFN-24L, 4 mm x 4 mm	Tape & Reel	5000

TAPE AND REEL INFORMATION



DIMENSIONS AND PIN1 ORIENTATION

Device	Package Type	D0 (mm)	W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant	Quantity
HUSB363-XXXXX-QN16R	QFN4X4-16L	330.00	12.40	4.30	4.30	1.10	8.00	4.00	12.00	Q1	5000
HUSB363-XXXXX-QN24R	QFN4X4-24L	330.00	12.40	4.30	4.30	1.10	8.00	4.00	12.00	Q1	5000

All dimensions are nominal

Figure9. tape and reel

IMPORTANT NOTICE

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